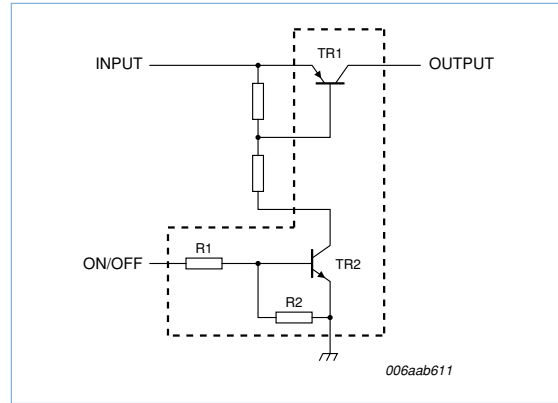
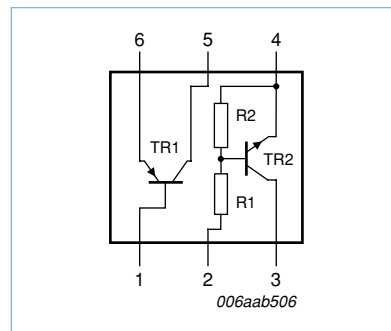


Application example

A small control (on/off) current (= base TR2) switches a high output (= collector TR1) current

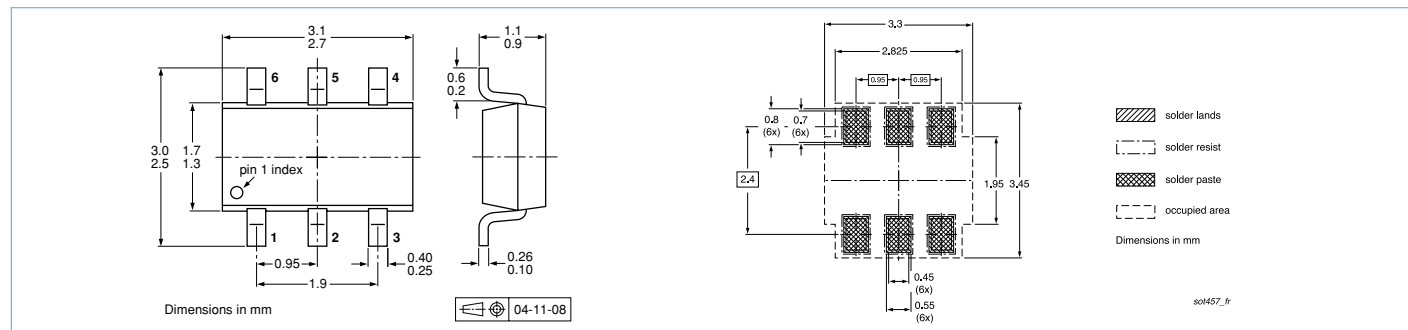


Configuration for new load switch families in SOT457



Modification of pinning compared to existing load switches due to optimized lead frame.

Outline drawing and soldering footprint of SOT457 (SC-74)



www.nxp.com

founded by

PHILIPS

© 2009 NXP B.V.

All rights reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Date of release: July 2009
Document order number: 9397 750 16754
Printed in the Netherlands



NXP low V_{CEsat} load switches
PBL520xD and PBL560xD

Load switches with best-in-class current capability and lowest saturation voltage

Designed to simplify circuit design and reduce pick-and-place costs, these load switches combine an energy-saving low V_{CEsat} transistor with a resistor-equipped transistor (RET) in a single package. They're housed in SOT457 packages, offer the highest current-per-footprint ratings on the market, and are ideal for switching positive supply rails or ground-referenced loads.

Key features

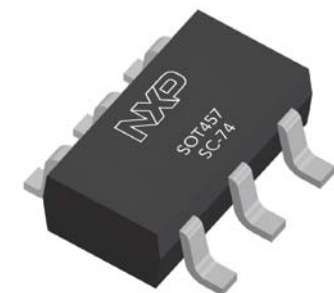
- ▶ PNP low V_{CEsat} transistor and NPN RET in small SOT457 SMD package
- ▶ V_{CEO} of 20 V or 60 V, with four resistor values available
- ▶ First to offer improved current capability
 - I_C : 1.8 A for 20 V
 - I_C : 1.5 A for 60 V
- ▶ Highest current per footprint area in loadswitch portfolio: 160 mA/mm² vs. 80-90 mA/mm²
- ▶ Reduction of V_{CEsat} by ~ 50% vs. last generation

Key benefits

- ▶ Space-saving solution
- ▶ Simplifies circuit design, reduces component count from four to one
- ▶ Fewer solder points for increased reliability
- ▶ Reduces pick-and-place costs
- ▶ Low threshold voltage (<1 V) compared to MOSFET
- ▶ AEC-Q101 qualified

Key applications

- ▶ Supply-line switches
- ▶ Battery-charger switches
- ▶ High-side switches for LEDs, drivers, and backlights
- ▶ Portable equipment



NXP
founded by Philips

NXP
PBL52021D
20 V, 1.8 A, R1/2 = 2.2 kΩ,
SOT457 (SC-74)

NXP
PBL56021D
60 V, 1.5 A, R1/2 = 2.2 kΩ,
SOT457 (SC-74)

NXP
PBL52022D
20 V, 1.8 A, R1/2 = 4.7 kΩ,
SOT457 (SC-74)

NXP
PBL56022D
60 V, 1.5 A, R1/2 = 4.7 kΩ,
SOT457 (SC-74)

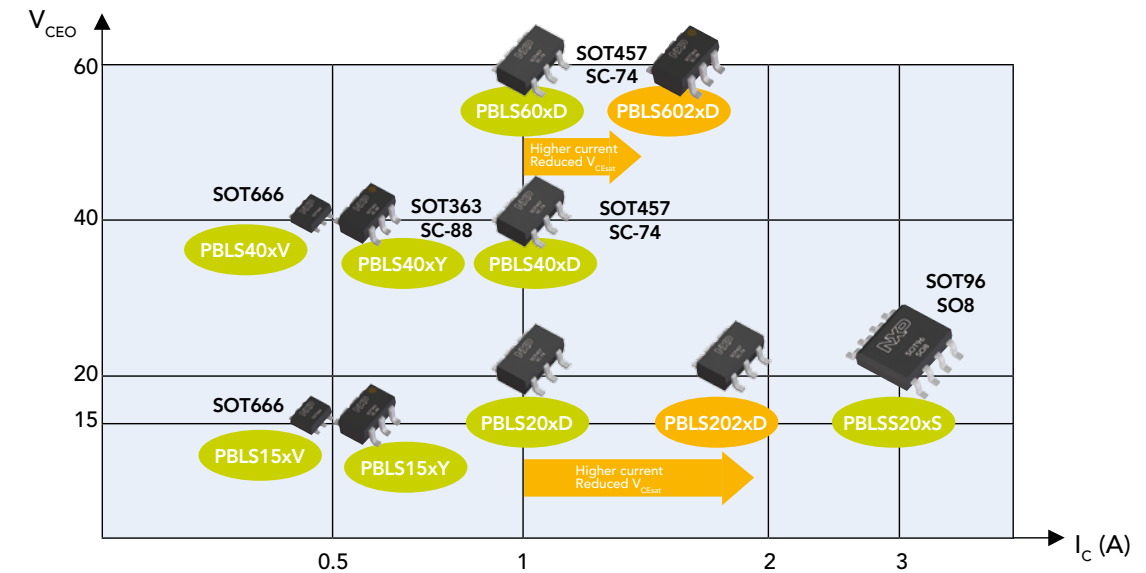
NXP
PBL52023D
20 V, 1.8 A, R1/2 = 10 kΩ,
SOT457 (SC-74)

NXP
PBL56023D
60 V, 1.5 A, R1/2 = 10 kΩ,
SOT457 (SC-74)

NXP
PBL52024D
20 V, 1.8 A, R1/2 = 22 kΩ,
SOT457 (SC-74)

NXP
PBL56024D
60 V, 1.5 A, R1/2 = 22 kΩ,
SOT457 (SC-74)

Portfolio extension: low V_{CEsat} load switches with improved current capability



Selection guide: low V_{CEsat} load switches

		Package				
		SOT96 (SO8)	SOT457 (SC-62)	SOT363 (SC-88)	SOT666	
Size (mm)		4.9 x 3.9 x 1.75	2.9 x 1.5 x 1.0	2.0 x 1.25 x 0.95	1.6 x 1.2 x 0.55	
P_{tot} (mW)		1500 ¹⁾	600 ¹⁾	300 ²⁾	300 ²⁾	
V_{CEO} (V)	I_C (A)	V_{CEsat} typ (mV); $I_C = 0.5$ A	R1, R2 (kΩ)			
15	0.5	250	2.2		PBL1501Y	PBL1501V
			4.7		PBL1502Y	PBL1502V
			10		PBL1503Y	PBL1503V
			22		PBL1504Y	PBL1504V
20	1	150	2.2		PBL2001D	
			4.7		PBL2002D	
			10		PBL2003D	
			22		PBL2004D	
20	1.6	70	2.2		PBL2021D	
			4.7		PBL2022D	
			10		PBL2023D	
			22		PBL2024D	
20	3	75	2.2	PBL2001S		
			4.7	PBL2002S		
			10	PBL2003S		
40	1	170	2.2		PBL4001D	
			4.7		PBL4002D	
			10		PBL4003D	
			22		PBL4004D	
			47		PBL4005D	
60	1	180	2.2		PBL6001D	
			4.7		PBL6002D	
			10		PBL6003D	
			22		PBL6004D	
			47		PBL6005D	
60	1.3	100	2.2		PBL6021D	
			4.7		PBL6022D	
			10		PBL6023D	
			22		PBL6024D	

¹⁾ Device mounted on a ceramic PCB, Al₂O₃, standard footprint

²⁾ Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint

Types in **bold blue** represent new products and are included as samples